



Material Content Data Sheet



Sales Product Name	ISO1H801G			Issued	29. August 2013			
MA#	MA000719956							
Package	PG-DSO-36-21			Weight*	2046.14 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	19.020	0.93	0.93	9295	9295
leadframe	inorganic material	phosphorus	7723-14-0	0.383	0.02		187	
	non noble metal	zinc	7440-66-6	1.533	0.07		749	
	non noble metal	iron	7439-89-6	30.652	1.50		14980	
wire	non noble metal	copper	7440-50-8	1244.598	60.83	62.42	608266	624182
	noble metal	gold	7440-57-5	3.941	0.19	0.19	1926	1926
	encapsulation	organic material	carbon black	1333-86-4	1.438	0.07		703
encapsulation	plastics	epoxy resin	-	66.129	3.23		32319	
	inorganic material	silicondioxide	60676-86-0	651.225	31.83	35.13	318270	351292
leadfinish	non noble metal	tin	7440-31-5	16.150	0.79	0.79	7893	7893
plating	noble metal	silver	7440-22-4	0.741	0.04	0.04	362	362
glue	plastics	Polyimide	26023-21-2	0.292	0.01	0.01	143	143
solder	noble metal	silver	7440-22-4	0.151	0.01		74	
	non noble metal	tin	7440-31-5	0.100	0.00		49	
	non noble metal	lead	7439-92-1	9.789	0.48	0.49	4784	4907
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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